

3C930 U.S. PTO  
10/064644  
08/02/02

U.S. UTILITY Patent Application

PATENT NUMBER and  
ISSUE DATE

2112

APPL NUM 10064644	FILING DATE 08/02/2002	CLASS 257	SUBCLASS 77E	GAU 281T	EXAMINER 3826 ELK/llaw
<b>**APPLICANTS:</b> Hsu Chi-Hsing;					
<b>**CONTINUING DATA VERIFIED:</b>					
<b>** FOREIGN APPLICATIONS VERIFIED:</b> TAIWAN 91208321 06/05/2002					
PG-PUB <input type="checkbox"/>		DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>	
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no		35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no		ATTORNEY DOCKET NO 9223-US-PA	
Verified and Acknowledged Examiners's initials					
TITLE : Flip-chip package substrate and flip chip die					

U.S. DEPT. OF COMM. PAT. & TM. PTO-436L (Rev. 12-97)

<b>NOTICE OF ALLOWANCE MAILED</b>		<b>CLAIMS ALLOWED</b>	
		Total Claims	
		Print Claim for O.G.	
<b>ISSUE FEE</b>		<b>DRAWING</b>	
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg.
		Print Fig.	
<input type="checkbox"/> <b>TERMINAL DISCLAIMER</b>		Primary Examiner	
		<b>PREPARED FOR ISSUE</b>	
		Application Examiner	
<b>WARNING:</b> The information disclosed herein may be restricted. Unauthorized disclosure may be prohibited by the United States Code Title 35, Sections 122, 181 and 368, Possession outside the U.S. Patent & Trademark Office is restricted to authorized employees and contractors only.			

FILED WITH:

☐ DISK (CRF)

☐ CD-ROM

(Attached in pocket on right inside flap)